



In re Application of: Shinya SOEDA
 Application No. 10/077,767
 Filed: February 20, 2002
 For: SEMICONDUCTOR DEVICE AND METHOD OF FABRICATING THE SAME

COMMISSIONER FOR PATENTS
 Washington, D.C. 20231

Sir:

Transmitted herewith is a response to an office action in the subject application.

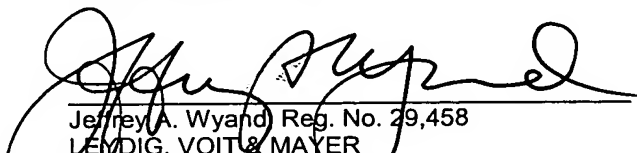
- ☐ Applicants claim small entity status of this application under 37 CFR 1.27.
- ☒ Petition for Extension of Time
- ☐ Applicants petition for a one-month extension of time under 37 CFR 1.136, the fee for which is \$110.00 (enclosed).
- ☒ Applicants believe that no petition for an extension of time is necessary. However, to the extent that such petition is deemed necessary, Applicants hereby petition for a sufficient extension of time to render the present submission timely. Please charge Deposit Account No. 12-1216 for the appropriate petition fee.
- ☒ No additional claim fee is required.
- ☐ Other:

The claim fee has been calculated as shown below:

					SMALL ENTITY		OTHER THAN A SMALL ENTITY		
			CLAIMS REMAINING AFTER AMENDMENT	HIGHEST NUMBER PREVIOUSLY PAID FOR	EXTRA CLAIMS PRESENT	RATE	ADDIT. CLAIM FEE	RATE	ADDIT. CLAIM FEE
TOTAL			MINUS		=	x 9=	\$	x 18=	\$
INDEPENDENT			MINUS		=	x 42=	\$	x 84=	\$
<input type="checkbox"/>	FIRST PRESENTATION OF MULTIPLE CLAIM					+ 140=	\$	+ 280=	\$
						TOTAL	\$	TOTAL	\$

- ☐ Please charge my Deposit Account No. 12-1216 in the amount of \$. A duplicate copy of this sheet is attached.
- ☐ A check in the amount of \$ is attached.
- ☒ The Commissioner is hereby authorized to charge any deficiencies in the following fees associated with this communication or credit any overpayment to Deposit Account No. 12-1216. A duplicate copy of this sheet is attached.
- ☒ Any filing fees under 37 CFR 1.16 for the presentation of extra claims.
- ☒ Any patent application processing fees under 37 CFR 1.17.

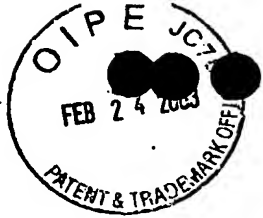
Respectfully submitted,


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Date: February 24, 2003
 JAW/tph
 Amendment or ROA Transmitted (Revised 12/31/02)

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PATENT
Attorney Docket No. 401572/SAKAI

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Shinya SOEDA

Application No. 10/077,767 ✓

Art Unit: 2811

Filed: February 20, 2002

Examiner: M. Prenty

For: SEMICONDUCTOR DEVICE AND
METHOD OF FABRICATING THE
SAME

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RESPONSE TO OFFICE ACTION

Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

In response to the Office Action dated November 22, 2002, please enter the following amendments and consider the following remarks.

AMENDMENTS

IN THE CLAIMS:

Please replace the indicated claims with:

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B1 017
1. (Twice Amended) A semiconductor device comprising:
a semiconductor substrate having at least one DRAM region and one logic region;
a resistor group including a plurality of resistors located in said logic region;
a metal interconnection layer opposite said resistor grouping said logic region; and
a metallic layer disposed between said resistor group and said metal interconnection
layer in said logic region as a shielding layer and partially disposed within said DRAM
region.

2. (Twice Amended) The semiconductor device according to claim 1, wherein said
metallic layer is a bit line layer in said DRAM region.

3. (Twice Amended) The semiconductor device according to claim 1, comprising
a stacked capacitor in said DRAM region and including a lower capacitor electrode layer, a
dielectric film, and an upper capacitor electrode layer, said upper capacitor electrode layer